LISTING OF THE CLAIMS

| | |
|---|---|
| CLAIM 1 | CANCELED |
| CLAIM 2 | CANCELED |
| CLAIM 3 | ORIGINAL |
| CLAIM 4 | ORIGINAL |

TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1. CANCELED

2. CANCELED.

3. (original) A method for laser marking the inactive surface of a semiconductor silicon die or wafer comprising

   (a) providing a sprayable adhesive composition having a viscosity within the range of 0.5 Pa.s to 5.0 Pa.s, containing at least one colored filler present in an amount up to 50% by weight of the adhesive composition,

   (b) spraying or jetting the adhesive composition onto the inactive surface of the semiconductor silicon die or wafer to a thickness within the range of 12.5 µm to 150 µm

   (c) curing the adhesive composition

   (d) marking the die or wafer by using a laser to burn or cut a mark or fiducial into the adhesive.

4. (original) The method according to claim 3 in which the sprayable adhesive is an epoxy resin or a combination of an electron donor resin and an electron acceptor resin.